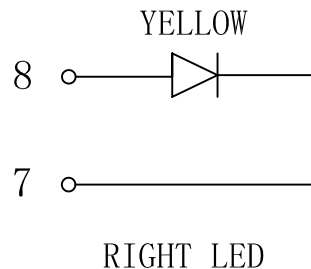
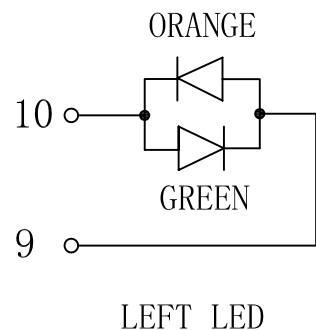
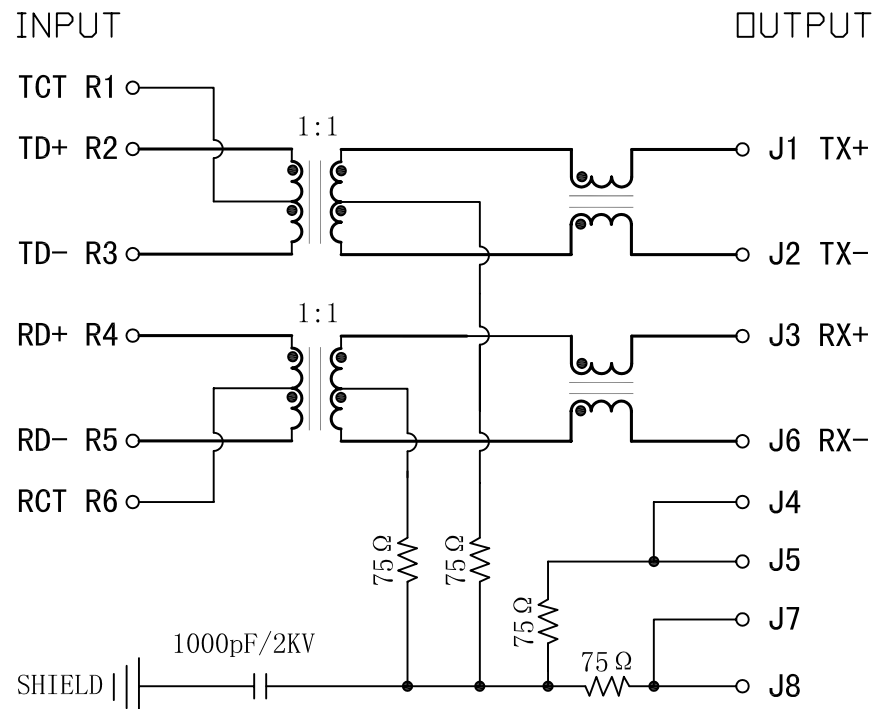


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/07/02	



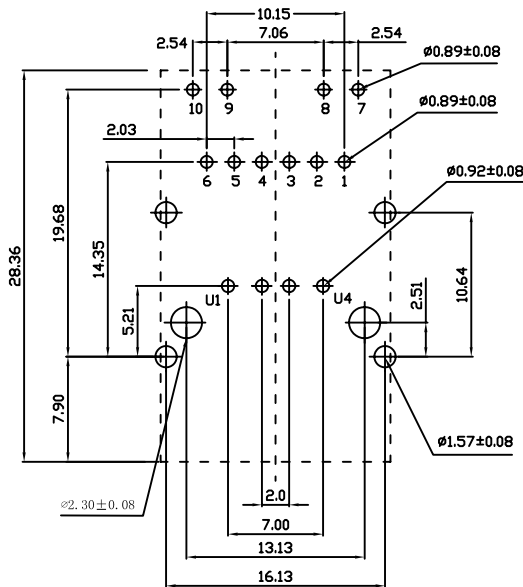
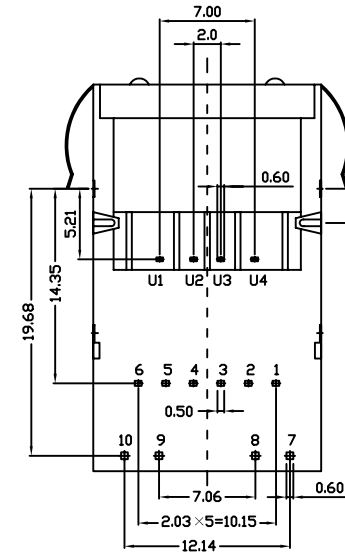
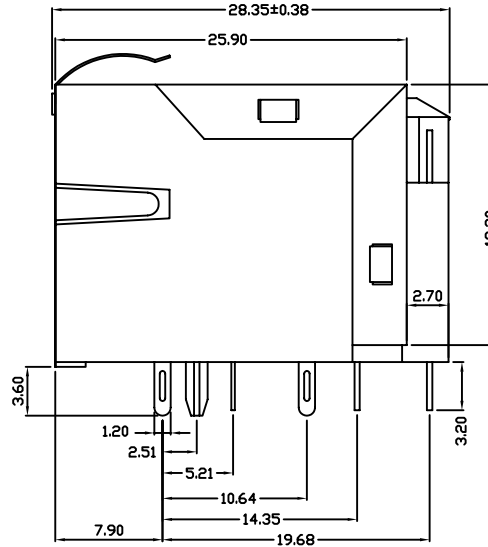
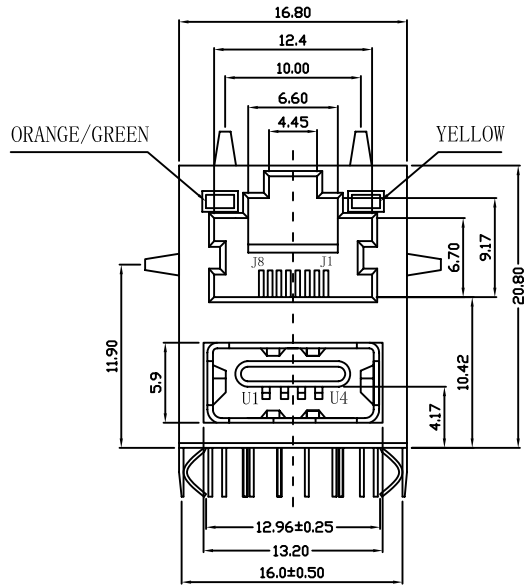
Transmitter filter & Receiver filter

- Type: Balance low pass 100Ω impedance
- INDUCTANCE @ 100KHz, 0.1V, 8mA, DC Bias
Input (R2-R3), Input (R4-R5): 350uH Min
- HIPOT TEST
Input (R2-R3) to Output (C1-C2):
1500VAC, 60sec
Input (R4-R5) to Output (C3-C6):
1500VAC, 60sec
- INSERTION LOSS:
-1.0dB MAX @ 1.0MHz TO 100MHz
- RETURN LOSS:
-18dB Min. load 100Ω @ 1MHz TO 30MHz
-16dB Min. load 100Ω @ 30MHz TO 60MHz
-12dB Min. load 100Ω @ 60MHz TO 80MHz
- CROSS TALK:
-30dB Min @ 1MHz TO 100MHz
- COMMON MODE REJECTION:
-30dB Min @ 1MHz TO 100MHz
- Operating Temperature: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$.

X:X	± 0.30	APPD:	
X:XX	± 0.20	CHKD:	
X:XXX	± 0.10	DR: TOM	TITLE: RJ45/Single USB Jack With 10/100 Magnetics
ANGLES	$\pm 1^{\circ}$	UNIT: mm	PART NO.:
	SCALE: 2/1	SHEET: 1/2	REV: A DWG NO.:

Mechanical :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/07/02	



Suggested PCB Layout (TOP VIEW)

NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
 Housing: Thermoplastic UL94V-0
 Contact/Shield: Copper alloy
 Shield plating: Nickel
 RJ-45 Contact plating: Gold 6 micro-inches min.
 In contact area
 USB Contact plating: Gold 6 micro-inches min.
 In contact area
4. Wave solder tip temperature and time: 265°C MAX, 5 Sec MAX.



X:X	±0.30	APPD:	
X:XX	±0.20	CHKD:	
X:XXX	±0.10	DR: TOM	TITLE: RJ45/Single USB Jack With 10/100 Magnetics
ANGLES	±1°	UNIT: mm	PART NO.:
	SCALE: 2/1	SHEET: 2/2	REV: A DWG NO.: